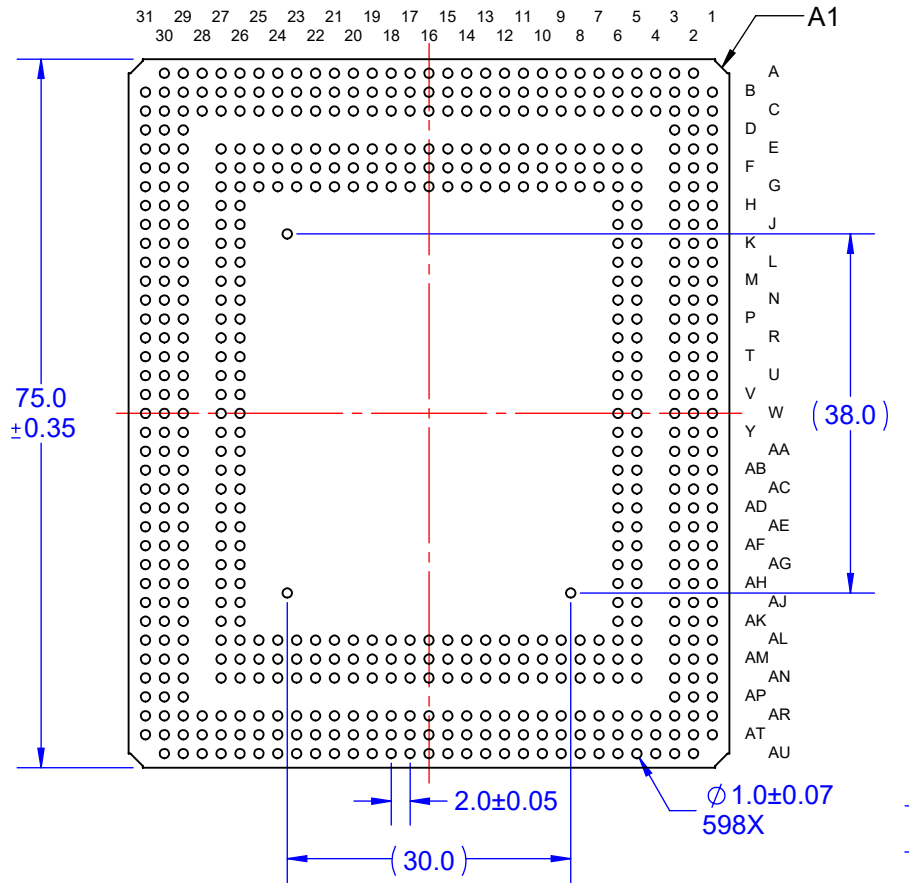
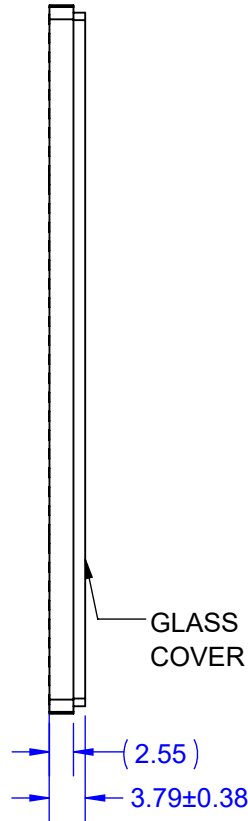


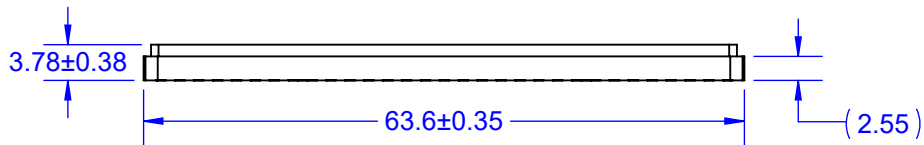
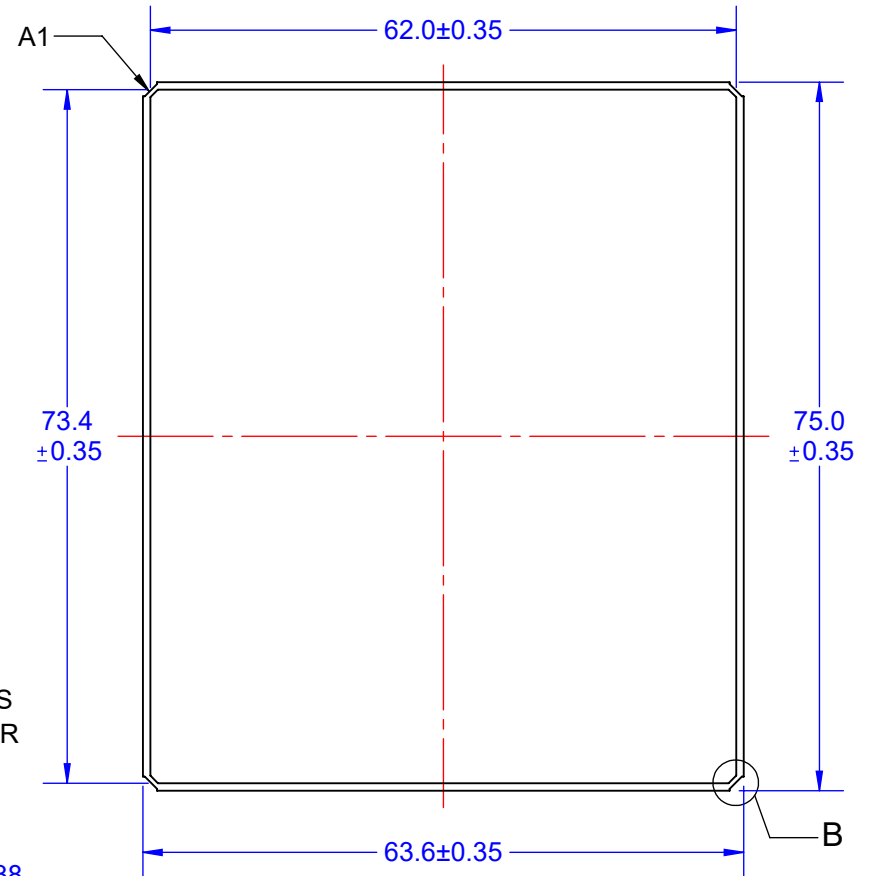
### BOTTOM VIEW



### SIDE VIEW



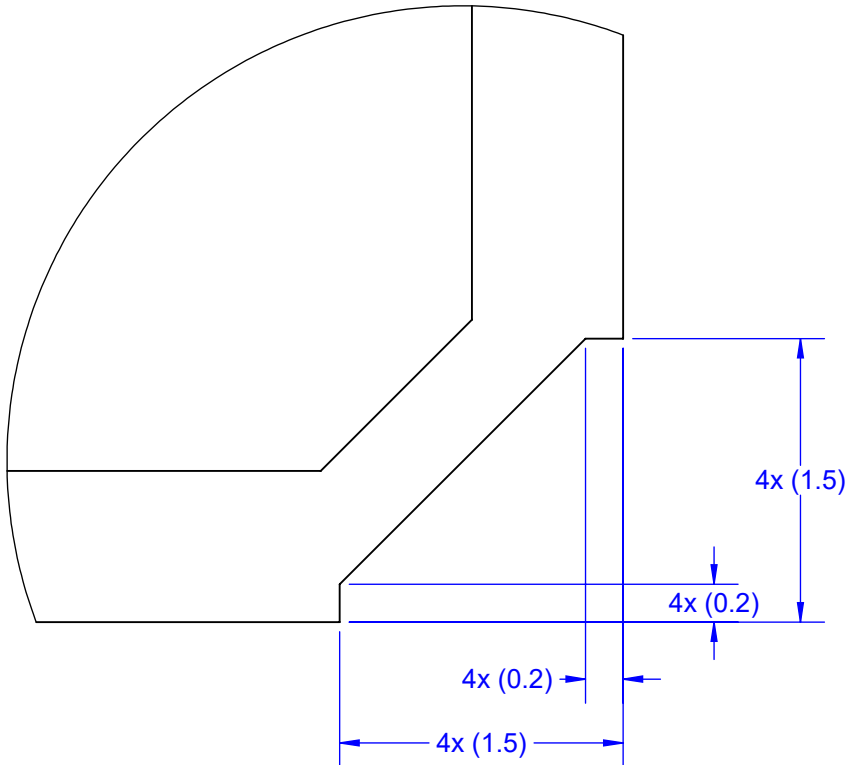
### TOP VIEW



Notes: (Unless Otherwise Specified).  
 1) DIMENSIONS ARE MILLIMETER.  
 2) SONY IMX661-AAQR-C CMOS SENSOR.

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T.Au	2/10/2021				
ENG M. Hart	2/10/2021	TITLE CLGA598 PITCH 2.0mm SENSOR CAMERA			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		1.75:1	A	160084	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 7
REVISED					

**DETAIL B  
CORNERS (4X)**



**TopLine®**

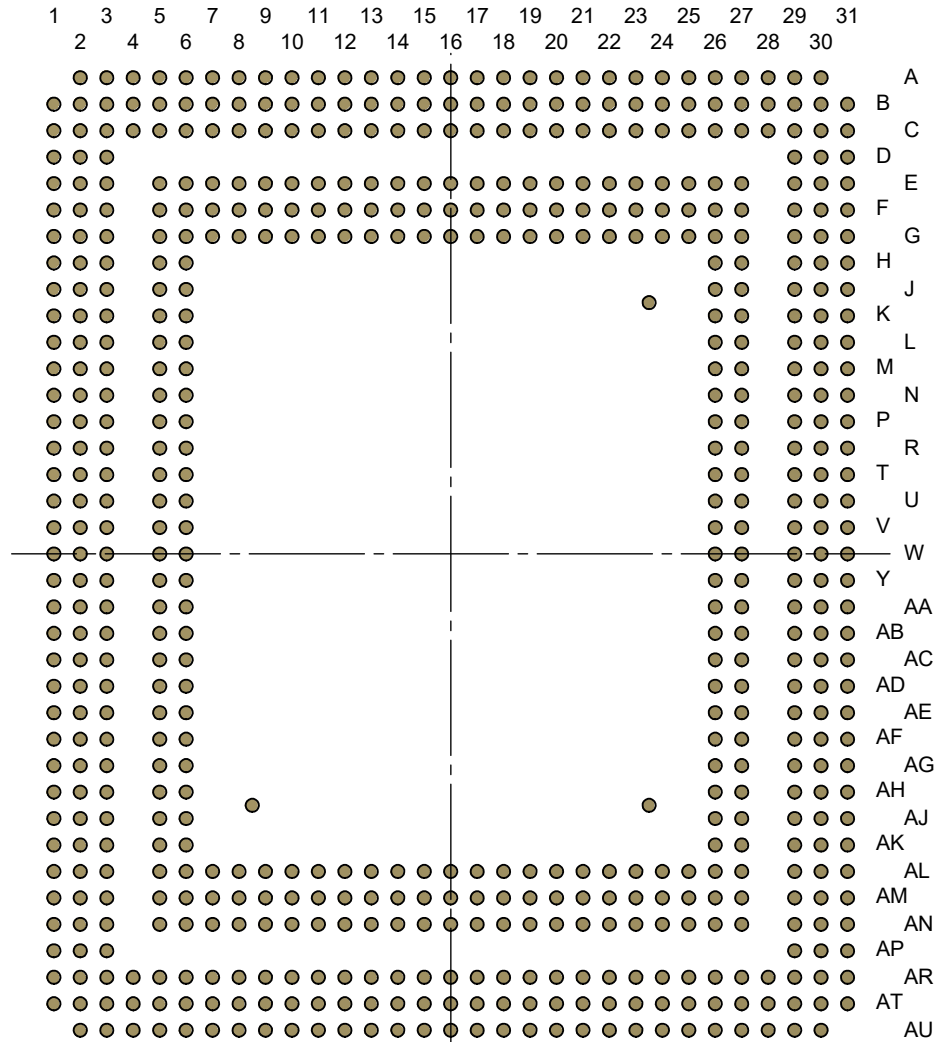
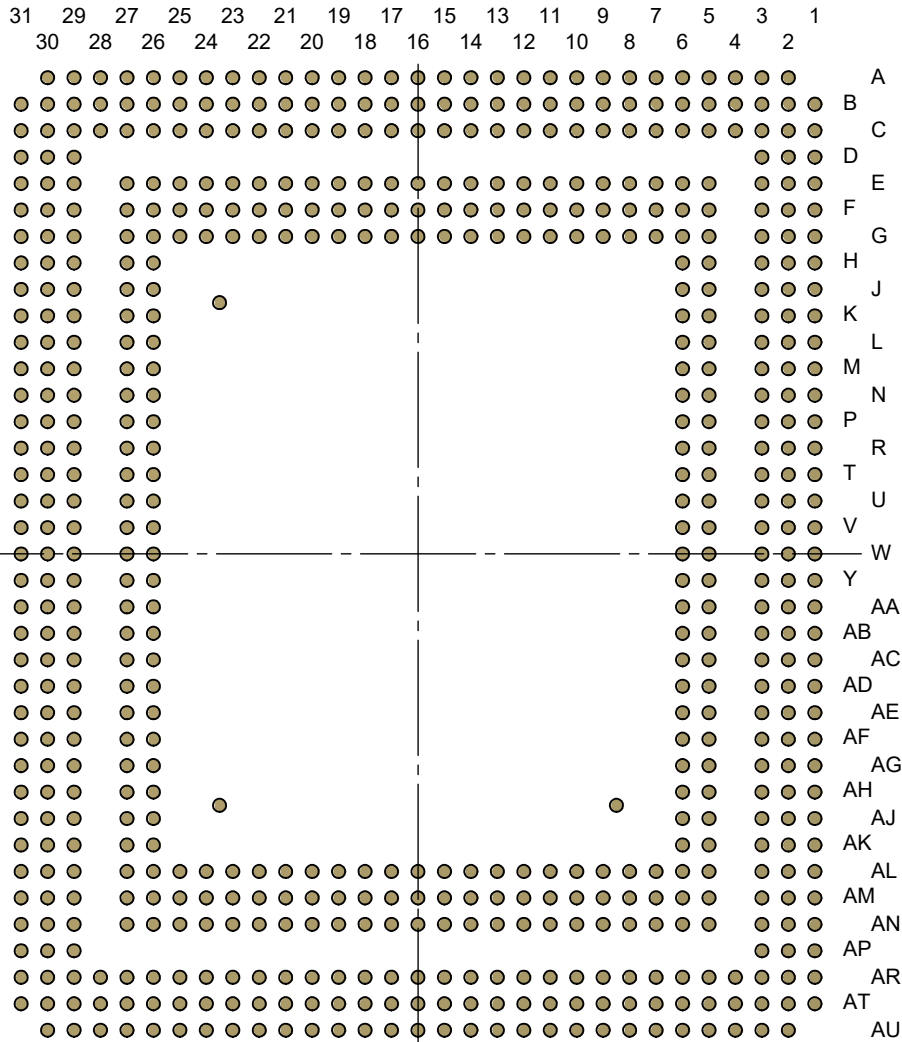
TITLE CLGA598 PITCH 2.0mm  
SENSOR CAMERA

SCALE 25:1	SIZE A	DRAWING NO. 160084	REV A
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# PAD PATTERN

## COLUMN (PAD) VIEW

## BOTTOM X-RAY VIEW FROM TOP

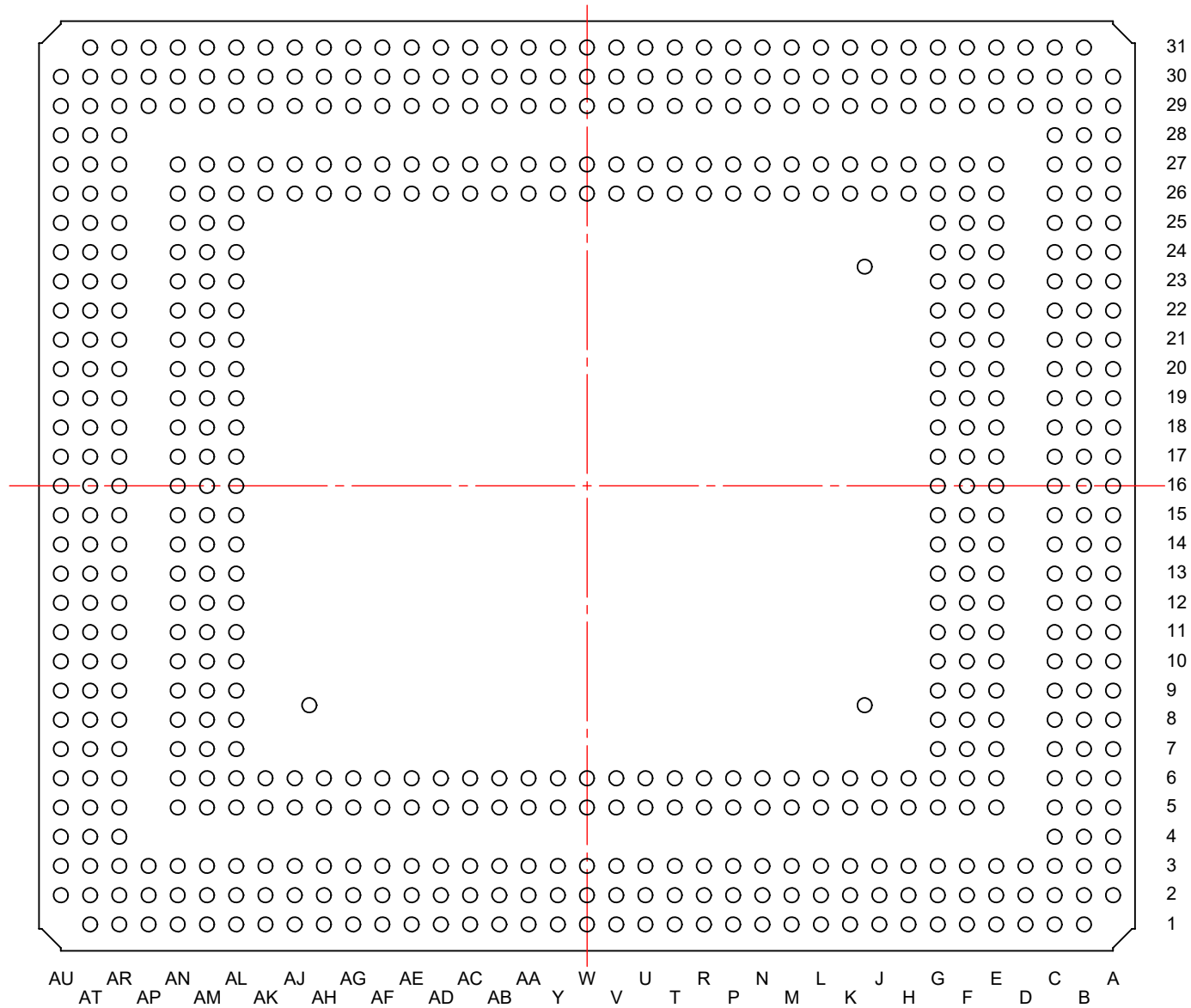


**TopLine®**

TITLE CLGA598 PITCH 2.0mm  
SENSOR CAMERA

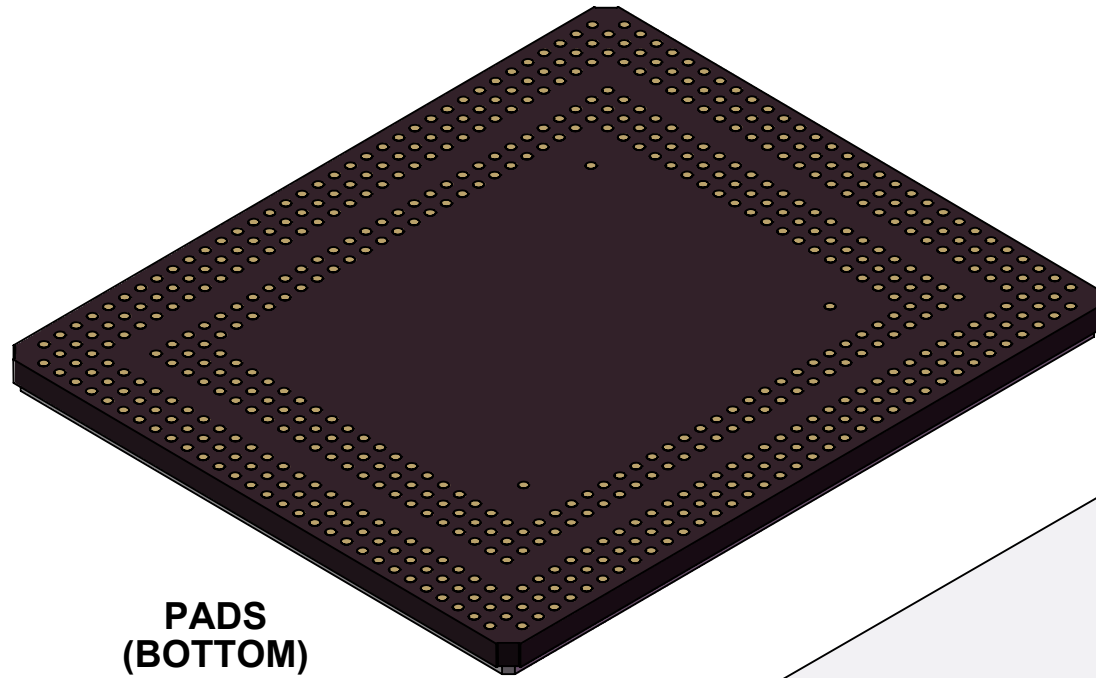
SCALE 1.75:1	SIZE A	DRAWING NO. 160084	REV A
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# PAD VIEW

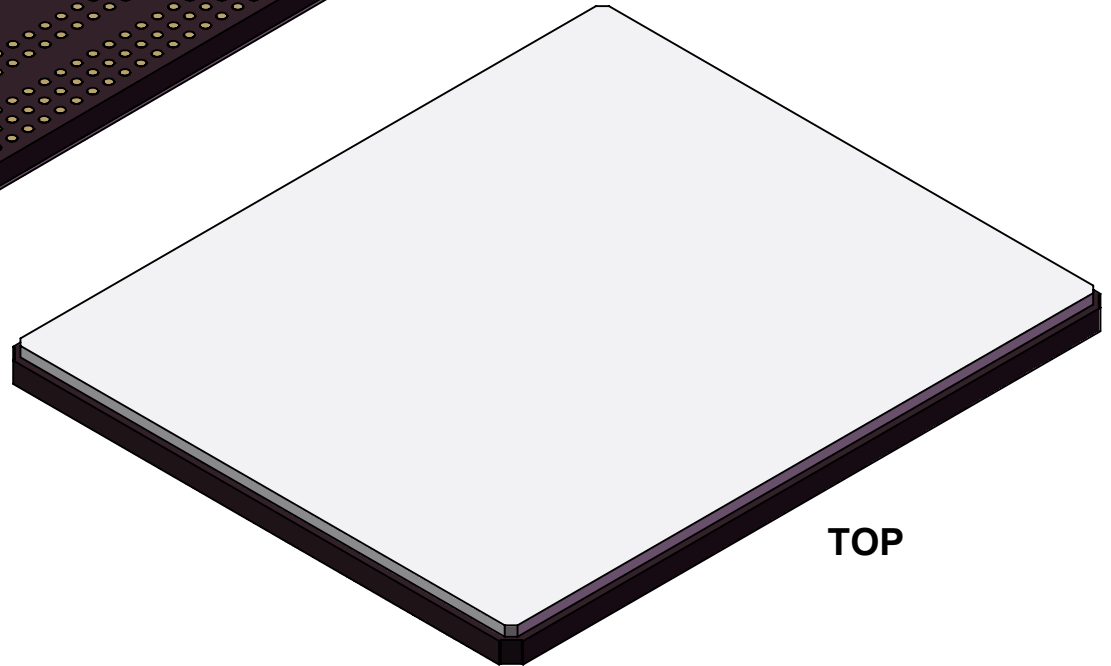


<b>TopLine®</b>			
TITLE		CLGA598 PITCH 2.0mm SENSOR CAMERA	
SCALE	SIZE	DRAWING NO.	REV
2.25:1	A	160084	A
DO NOT SCALE DRAWING			SHEET 4 OF 7

# MODEL



**PADS  
(BOTTOM)**

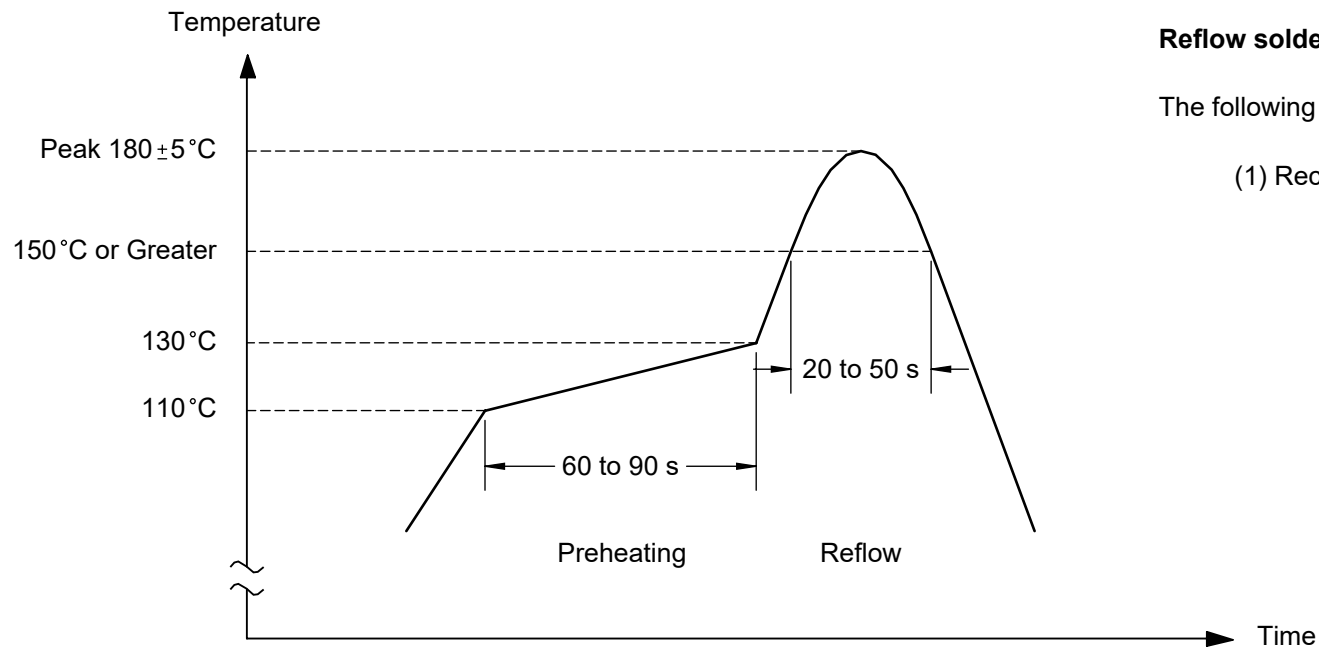


**TOP**

<b>TopLine<sup>®</sup></b>			
TITLE		CLGA598 PITCH 2.0mm SENSOR CAMERA	
SCALE	SIZE	DRAWING NO.	REV
3:2	A	160084	A
DO NOT SCALE DRAWING			SHEET 5 OF 7

## REFLOW TEMPERATURE APPLICATION NOTES

Control item	Profile (at part side surface)
1. Preheating	110 to 130 °C 60 to 90 s
2. Temperature up (down)	±4 °C/s or less
3. Reflow temperature	150 °C or Greater 20 to 50 s Max. 5 °C/s
4. Peak temperature	Max. 180 ± 5 °C



### Reflow soldering conditions

The following items should be observed for reflow soldering.

- (1) Recommended temperature profile for reflow soldering.

<b>TopLine®</b>			
TITLE CLGA598 PITCH 2.0mm SENSOR CAMERA			
SCALE NONE	SIZE A	DRAWING NO. 160084	REV A
DO NOT SCALE DRAWING			SHEET 6 OF 7


## APPLICATION NOTES

### (A) Reflow conditions

- (1) Maximum temperature of the upper surface of the seal glass resin adhesive portion of the package does not exceed 180°C.
- (2) Maximum reflow soldering only one time.
- (3) Finish reflow soldering within 72 h after unsealing the degassed packing.  
Store the products under the condition of temperature of 30°C or less and humidity of 70% RH or less after unsealing the package.
- (4) Perform re-baking only one time under the condition at 125°C for 24 h.
- (5) Note that condensation on glass or discoloration on resin interfaces may occur if the actual temperature and time exceed the conditions mentioned above.

### (B) Other Notes:

- (1) Do not expose to strong light (sun rays) for long periods, as the color filters of color devices will be discolored.
- (2) Exposure to high temperature or humidity will affect the characteristics. Accordingly avoid storage or use in such conditions.
- (3) This product is precision optical parts, so care should be taken to not apply excessive mechanical shocks or force.
- (4) Note that imaging characteristics of the sensor may be affected when approaching strong electromagnetic wave or magnetic field during operation.
- (5) Note that image may be affected by the light leaked to optical black when using an infrared cut filter that has transparency in near infrared ray area during shooting subjects with high luminance.
- (6) Note that X-ray inspection may damage characteristics of the sensor.

			
TITLE		CLGA598 PITCH 2.0mm SENSOR CAMERA	
SCALE	SIZE	DRAWING NO.	REV
NONE	A	160084	A
DO NOT SCALE DRAWING			SHEET 7 OF 7